

Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild guestions@onsemi.com.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer



January 2008

FDC855N

Single N-Channel, Logic Level, PowerTrench® MOSFET 30V, 6.1A, 27m Ω

Features

- Max $r_{DS(on)} = 27m\Omega$ at $V_{GS} = 10V$, $I_D = 6.1A$
- Max $r_{DS(on)} = 36m\Omega$ at $V_{GS} = 4.5V$, $I_D = 5.3A$
- SuperSOTTM -6 package: small footprint (72% smaller than standard SO-8; low profile (1mm thick).
- RoHS Compliant

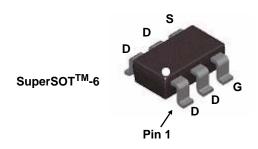


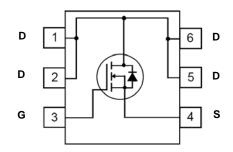
General Description

This N-Channel Logic Level MOSFET is an efficient solution for low voltage and battery powered applications. Utilizing Fairchild Semiconductor's advanced PowerTrench® process, this device possesses minimized on-state resistance to optimize the power consumption. They are ideal for applications where in-line power loss is critical.

Application

■ Power Management in Notebook, Hard Disk Drive





MOSFET Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DS}	Drain to Source Voltage		30	V
V _{GS}	Gate to Source Voltage	±20	V	
	Drain Current -Continuous $T_A = 25^{\circ}C$ (Note 1a)		6.1	۸
'D	-Pulsed		20	A
D	Power Dissipation (Steady State)	(Note 1a)	1.6	W
P_{D}	Power Dissipation (Steady State)	(Note 1b)	0.8	VV
T _J , T _{STG}	Operating and Storage Junction Temperature Range	Operating and Storage Junction Temperature Range		°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	30	°C/M
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	78	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
.855	FDC855N	SuperSOT-6	7"	8 mm	3000 units

Units

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted Parameter

Off Char	acteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$, referenced to 25°0		24		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 24V,$ $T_{C} = 129$	5°C		1 250	μА
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA

Test Conditions

Min

Тур

Max

On Characteristics

Symbol

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1.0	2.0	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$, referenced to 25°C		-6		mV/°C
r _{DS(on)} Static Drain to Source On Resistance	$V_{GS} = 10V, I_D = 6.1A$		20.7	27.0		
	$V_{GS} = 4.5V, I_D = 5.3A$		28.2	36.0	mΩ	
		$V_{GS} = 10V$, $I_D = 6.1A$, $T_J = 125$ °C		30.1	39.3	
g _{FS}	Forward Transconductance	$V_{DD} = 10V, I_D = 6.1A$		20		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 45V V 0V	493	655	pF
C _{oss}	Output Capacitance	$V_{DS} = 15V, V_{GS} = 0V,$ f = 1MHz	108	145	pF
C _{rss}	Reverse Transfer Capacitance	1 - 11/11/2	62	95	pF
R_q	Gate Resistance	f = 1MHz	1.0		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	.,	6	12	ns
t _r	Rise Time	$V_{DD} = 15V, I_D = 6.1A,$ $V_{GS} = 10V, R_{GEN} = 6\Omega$	2	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10V, R_{GEN} = 002$	14	23	ns
t _f	Fall Time		2	10	ns
Q_g	Total Gate Charge at 10V	V _{GS} =0Vto10V	9.2	13	nC
Qg	Total Gate Charge at 5V	$V_{GS} = 0V \text{ to } 5V$ $V_{DD} = 15V,$ $I_{D} = 6.1A$	4.9	7.0	nC
Q _{gs}	Gate to Source Charge	I _D = 6.1A	1.7		nC
Q _{gd}	Gate to Drain "Miller" Charge		3.1		nC

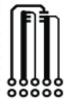
Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0V, I_S = 1.3A$ (Note 2)		0.80	1.2	V
t _{rr}	Reverse Recovery Time	I _E = 6.1A, di/dt = 100A/μs		17	31	ns
Q _{rr}	Reverse Recovery Charge	$I_{F} = 6.1A$, $di/dt = 100A/\mu S$		6	12	nC

^{1:} R_{0JA} is the sum of the junction-to-case and case-to- ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a. 78°C/W when mounted on a 1 in² pad of 2 oz copper.



b. 156°C/W when mounted on a minimum pad of 2 oz copper.

^{2:} Pulse Test: Pulse Width < 300 μ s, Duty Cycle < 2.0%.

Typical Characteristics T_J = 25°C unless otherwise noted

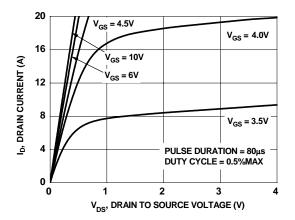


Figure 1. On-Region Characteristics

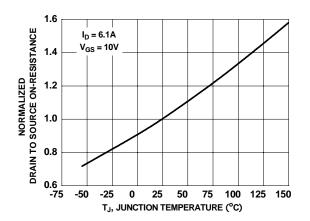


Figure 3. Normalized On-Resistance vs Junction Temperature

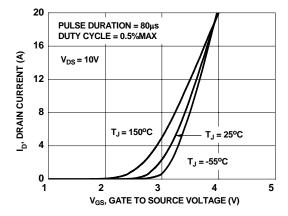


Figure 5. Transfer Characteristics

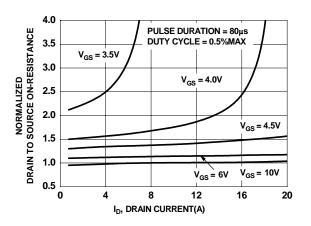


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

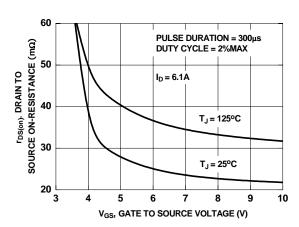


Figure 4. On-Resistance vs Gate to Source Voltage

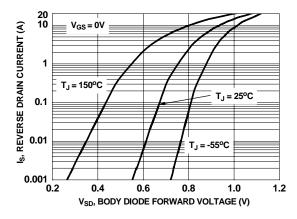


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25°C unless otherwise noted

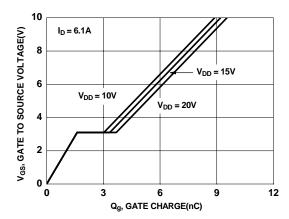


Figure 7. Gate Charge Characteristics

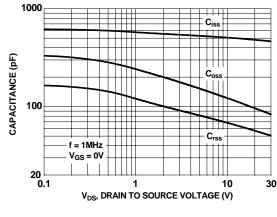


Figure 8. Capacitance vs Drain to Source Voltage

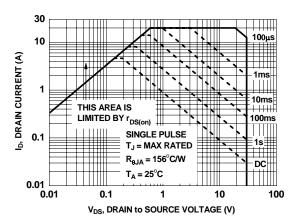


Figure 9. Forward Bias Safe Operating Area

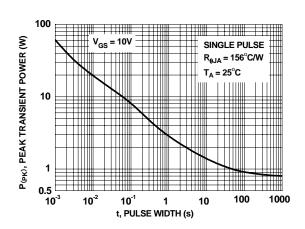


Figure 10. Single Pulse Maximum Power Dissipation

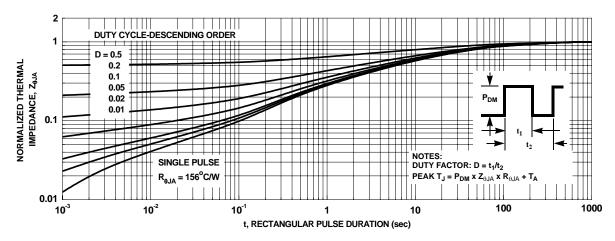


Figure 11. Transient Thermal Response Curve

Dimensional Outline and Pad Layout SYMM É 0.95 -0.953.00 2.80 ► A 1.00 MIN 6 4 B 3.00 2.60 2.60 1.70 1.50 3 0.50 0.30 0.95 ◆ 0.20 M C A B 0.70 MIN + 1.90 LAND PATTERN RECOMMENDATION (0.30) — SEE DETAIL A _1.10 MAX 1.00 0.70 C 0.20 0.08 0.10 △ 0.10 C NOTES: UNLESS OTHERWISE SPECIFIED GAGE PLANE THIS PACKAGE CONFORMS TO JEDEC MO-193. VAR. AA, ISSUE C, DATED JANUARY 2000. ALL DIMENSIONS ARE IN MILLIMETERS. 0.25 0.55 0.35 SEATING PLANE -0.60 REF DETAIL A SCALE: 50X MA06AREVD





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidianries, and is not intended to be an exhaustive list of all such trademarks.

FPS™ PDP-SPM™ SupreMOS™ $\mathsf{FRFET}^{\mathbb{R}}$ Power220® Build it Now™ SyncFET™ POWEREDGE® CorePLUS™ Global Power ResourceSM SYSTEM ® Green FPS™ CROSSVOLT™ Power-SPM™ The Power Franchise® PowerTrench® **CTL™** Green FPS™ e-Series™ puwer Current Transfer Logic™ GTO™ Programmable Active Droop™ i-Lo™ QFET® EcoSPARK® TinyBoost™ EZSWITCH™ * QSTM IntelliMAX™ TinyBuck™ ISOPLANAR™ QT Optoelectronics™ TinyLogic[®] MegaBuck™ Quiet Series™ TINYOPTO™ MICROCOUPLER™ RapidConfigure™ TinyPower™ **Ē**airchild[®] MicroFET™ SMART START™ TinyPWM™ Fairchild Semiconductor® SPM[®] MicroPak™ TinyWire™ FACT Quiet Series™ MillerDrive™ STEALTH™ µSerDes™ **FACT®** Motion-SPM™ SuperFET™ UHC® $\mathsf{FAST}^{\mathbb{R}}$ OPTOLOGIC® SuperSOT™-3 Ultra FRFET™ OPTOPLANAR® SuperSOT™-6 FastvCore™ UniFET™

* EZSWITCHTM and FlashWriter[®] are trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FlashWriter® *

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

SuperSOT™-8

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which,

 (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- A critical component in any component of a life support, device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

VCXTM

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information Formative or In Design		This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary First Production		This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild Semiconductor. The datasheet is printed for reference information only.

Rev. I33

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdt/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and exp

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ON Semiconductor:

FDC855N

ПОСТАВКА ЭЛЕКТРОННЫХ КОМПОНЕНТОВ

многоканальный

Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001 Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

Данный компонент на территории Российской Федерации Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

http://moschip.ru/get-element

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г. Москва, ул. Щербаковская д. 3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru moschip.ru_6 moschip.ru_4 moschip.ru_9